

Appl. No. 10/849,005
Response dated September 24, 2004
Reply to Office Action of June 25, 2004

Amendments to the Specification:

Please replace the paragraph beginning on page 2, line 9, with the following amended paragraph:

In a first device 100, an LED 101 is electrically mounted on a contact 102 by way of an electrically conductive medium 103. A bond wire 104 electrically connects the LED 101 to another contact 105. Both contacts 102, 105 extend horizontally through the body 106 of the device 100 (in the orientation shown in Figure 1A). Most of the body 106 is optically opaque, except for an inverted frusto-conical cavity 107, in which the LED 101, bond wire 104 and inner ends of the two contacts 102, 105 are encased in an optically clear plastic, with the edges of the cavity 107 acting as a reflector for light emitted from the LED 101. The two contacts 102, 105 extend horizontally outwards to the ends of the body 106, wrapping downwards around the lower halves of the sides 108 and back around under the bottom edges 109. During a solder reflow process to secure the device 100 to a substrate 110, the portions of the contacts 102, 105 running down the sides 108 are connected by solder joints 111 to the substrate 110, with the solder joints 111 against the outer vertical sides 108 of the LED device 100.

Please replace the paragraph beginning on page 9, line 18, with the following amended paragraph:

Both LEDs 508, 509 are mounted near the front end of the main contact 504 through an electrically conductive medium 526 and are separated from each other. Bond wires 528, 529 electrically connect the top of one LED 508 to the near end of one secondary contact 506 and the top of the other LED 509 to the near end of the other secondary contact 507.